	Appl	icant Initiated	l Interview R	equest Form		<u></u>
Application No.: 10/57 Examiner: A. WILLIA	·	First Named Applicant:		Hiroyuki TSUKASHIMA Status of Application: Final Rejection		
Tentative Participants: (1) Smith Sirisakorn	<u> </u>		Eric Moreh	<u> </u>		
Proposed Date of Interview: June 22, 20					10:00 AM	
Type of Interview Requ	iested:		(3) Video	Conference		
Exhibit To Be Shown or If yes, provide brief des				⊠ NC		
	<u></u>	Issues 7	Γο Be Discuss	ed		
Issues (Rej., Obj., etc)	Claims/ Fig. #s	Applied Reference(s)		Discussed	Agreed	Not Agreed
(1) §103(a) Rej.	Claims 1, 5 Figs. 5-9	U.S. Patent A Publication N 2002/005075 (Katsuzawa), Patent Application N 2004/020129	No. 52 , U.S. cation No.			
Continuation Sheet A Brief Description of Ar Hama and Katsuzawa due to its elastically d absorbing a componer diameter of the fixing	guments to be Pr a fail to at least tea deformable proper	ich "the second ties," as recited st due to havin	d in independe g a through-h	ent claim 1; and ole that has a le	l "the second co ength sufficientl	ontact is capable of ly greater than the
<u>independent claim 5.</u>	<u> </u>	<u></u>	. <u> </u>	<u> </u>	·	
An interview was cond	ucted on the abo	ve-identified a	application or	ı <u> </u>	<u> </u>	<u></u>
NOTE: This form should be c MPEP § 713.01).						
This application will r interview. Therefore, soon as possible.	not be delayed fr , applicant is adv	om issue beca ised to file a s	use of applica tatement of s	nnt's failure to ubstance of th	submit a write is interview (3'	ten record of this 7 CFR 1.133(b) as
(Applicant/Applicant's Representative Signature) (Examiner/SPE Signature)						